PAT-NO: JP401251791A

DOCUMENT-IDENTIFIER: JP 01251791 A

TITLE: MANUFACTURE OF WIRING BOARD

PUBN-DATE: October 6, 1989

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APPL-NO: JP63078425

APPL-DATE: March 31, 1988

INT-CL (IPC): H05K003/46

US-CL-CURRENT: 427/FOR.106

ABSTRACT:

PURPOSE: To make a high-density wiring using a 0.10mm wire and to obtain a multiwire wiring board which meets a condition Zo(impedance)=50ohms and has an excellent insulation deteriorating property, by covering a recessed portion of an insulating board, on which an inner circuit is formed, with material which is made by mixing several kinds of resins in specific proportions.

CONSTITUTION: A gland circuit 3 is formed as a power supply on an insulating board 2. A compound of 10∼50 pts.wt. epoxy resin whose molecular weight is

5,000 or more, 5∼25 pts.wt. alkylmelamine resin, 5∼50 pts.wt. saturated
polyester and 10∼40 pts.wt. inorganic fiber filler as against 100 pts.wt.
epoxy resin whose molecular weight is less than 5,000 and a **crosslinking** agent
are dissolved in a mixed solvent, dispersed, coated on a separation film and
cured to a state of **B stage**. This is placed on an inner circuit board 1 and is
applied with pressure and heat with an end plate piled on it, to form a resin
layer 4 with a smooth surface. Nextly, an adhesive resin layer 5 is laminated,
on the surface of which, a wire 6 is adhered to a desired wiring pattern.
Then, a thermosetting resin layer 7 is formed and a hole is made. On an inner
surface of the hole, a through-hole copper-plated layer 8 is formed.